

REPLACEMENT SHEET

Title: Integration of Annealing Capability Into Metal Deposition or CMP Tool

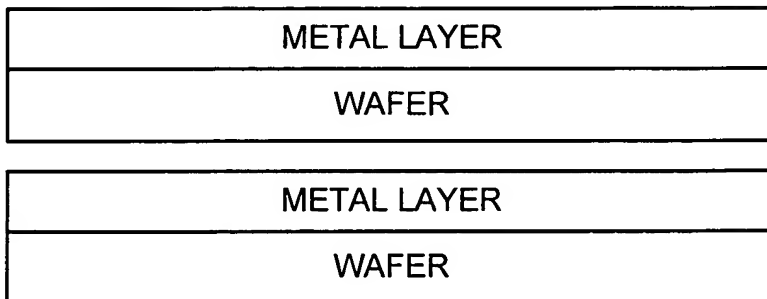
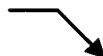
1<sup>st</sup> Named Inventor: Jick M. Yu

Application No.: 10/810,735

Docket No. 42P6934D

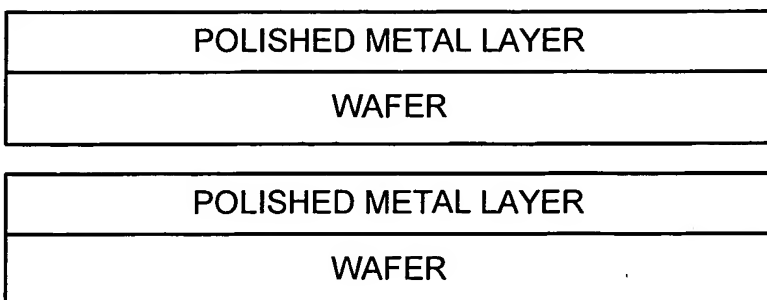
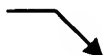


WAFERS HAVING  
METAL LAYERS  
DEPOSITED  
THEREON



*FIG. 7*

WAFERS HAVING  
METAL LAYERS  
THAT HAVE BEEN  
POLISHED



*FIG. 8*